



3D Packaging and Integration Global Technical Committee

Japan TC Chapter

Meeting Summary and Minutes

Japan Standards Spring Meeting 2023

March 15, 2023, 13:30-15:30[JST]

OVTCCM

TC Chapter Announcements

Next TC Chapter Meeting

Wednesday, June 21 13:30-16:00

OVTCCM

Table 1 Meeting Attendees

Italics indicate virtual participants.

Co-Chairs: Kazunori Kato (AiT), Masahiro Tsuruya (iNEMI), Haruo Shimamoto (AIST)

SEMI Staff: Mami Nakajo

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
<i>AIST</i>	<i>Shimamoto</i>	<i>Haruo</i>	<i>retired</i>	<i>Takahashi</i>	<i>Mark</i>
<i>AiT</i>	<i>Kato</i>	<i>Kazunori</i>	<i>SEMI Japan</i>	<i>Nakajo</i>	<i>Mami</i>
<i>iNEMI</i>	<i>Tsuruya</i>	<i>Masahiro</i>	<i>SEMI Japan</i>	<i>Okayasu</i>	<i>Nobuko</i>
<i>KOKUSAI ELECTRIC CORPORATION</i>	<i>Matsuda</i>	<i>Mitsuhiro</i>			

Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
None		

Table 3 Committee Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
Encapsulation Characteristics for Wafer Level Package and Panel Level Packaging Task Force	Disbanded

Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
None		None

#1 Note 1: **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 Note 2: **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Activities Approved by the GCS between meetings of the TC Chapter

#	Type	SC/TF/WG	Details
None			

Table 6 Authorized Activities

#	When	SC/TF/WG	Details
7020	SNARF	3D Packaging & Integration 5-Year Review TF	Reapproval of SEMI G94-0113 (Reapproved 1118) Specification for Coin-Stack Type Tape Frame Shipping Container for 300 mm Wafer
7019	SNARF	3D Packaging & Integration 5-Year Review TF	Reapproval of SEMI G64-1118, Specification for Full-Plated Integrated Circuit Leadframes (Au, Ag, Cu, Ni, Pd/Ni, Pd)

Table 7 Authorized Ballots

#	When	SC/TF/WG	Details
7020	Cycle 5-2023	3D Packaging & Integration 5-Year Review TF	Reapproval of G94-0113 (Reapproved 1118) Specification for Coin-Stack Type Tape Frame Shipping Container for 300 mm Wafer
7019	Cycle 5-2023	3D Packaging & Integration 5-Year Review TF	Reapproval of G64-1118, Specification for Full-Plated Integrated Circuit Leadframes (Au, Ag, Cu, Ni, Pd/Ni, Pd)

Table 8 SNARF(s) Granted a One-Year Extension

#	TF	Title	Expiration Date
None			

Table 9 SNARF(s) Abolished

#	TF	Title
None		

Table 10 Standard(s) to receive Inactive Status

Standard Designation	Title
None	

Table 11 New Action Items

Item #	Assigned to	Details
20230315-01	3D Packaging & Integration Steering Group	To call for new members to restart the activities of 3DP&I Steering Group to 3DP&I, Traceability and PIC Japan TC members.

Table 12 Previous Meeting Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20221214-01	3D Packaging & Integration 5 Year Review Task Force	To confirm documents and prepare SNARFs for these Reapproval Documents on the list by the next TC meeting.>Closed

1. Welcome, Reminders, and Introductions

Masahiro Tsuruya (iNEMI) called the meeting to order at 1:30 p.m. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 01-02_Required Element Nov 2022_E+J (new template)

2. Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion:	Approve the minutes as written
By / 2nd:	Kato Kazunori (AiT) / Mitsuhiro Matsuda (KOKUSAI ELECTRIC CORPORATION)
Discussion:	None
Vote:	4 in favor and 0 opposed. Motion passed.

Attachment: 02-01_20221214_3DPI-Japan_MeetingMinutes_approved

3. Liaison Reports

3.1 3D Packaging & Integration North America TC Chapter

Mami Nakajo (SEMI Japan) reported the 3D Packaging & Integration North America TC Chapter activity status based on the report as attached.

Attachment: 03-01_NA 3DP&I Liaison Report Nov2022 v1

3.2 3D Packaging & Integration Taiwan TC Chapter

Mami Nakajo (SEMI Japan) reported the 3D Packaging & Integration Taiwan TC Chapter activity status based on the report as attached.

Attachment: 03-02_3D P&I TW Liaison Report_20220902_v1

3.3 SEMI Staff Report

Mami Nakajo (SEMI) explained the SEMI Staff Report based on the report as attached.

Attachment: 03-03_Staff Report March 2022 v1

4. Ballot Review

None



5.Subcommittee and Task Force Reports

Haruo Shimamoto(AIST) took over the chair.

5.1 GCS Report

No report

5.2 3D Packaging & Integration 5 Year Review Task Force

Masahiro Tsuruya (iNEMI) reported the 3D Packaging & Integration 5 Year Review Task Force status as attached.

Attachment: 05-02_TF Report - 5yrs Review TF v2023_3_r1

5.3 3DS IC Bonded Layer Inspection Metrology Task Force

No update

5.4 Encapsulation Characteristics for Wafer Level Package and Panel Level Packaging Task Force

Masahiro Tsuruya (iNEMI) reported the status of Encapsulation Characteristics for Wafer Level Package and Panel Level Packaging Task Force as attached.

Motion:	Disband the Encapsulation Characteristics for Wafer Level Package and Panel Level Packaging Task Force
By / 2nd:	Masahiro Tsuruya (iNEMI) / Kato Kazunori (AiT)
Discussion:	None
Vote:	4 in favor and 0 opposed. Motion passed.

Attachment: 05-04_TF Report - PLP Encapsulation Characterisites TF v2023_3

5.5 Panel Level Packaging (PLP) Glass Carrier Task Force

Mark Takahashi (retired) announced that SEMI T24 which pertains to ID marks was published in December 2022.

5.6 3D Packaging & Integration Steering Group

Masahiro Tsuruya (iNEMI) proposed to decide the direction of future activities by the next committee meeting.

Action Item: 20230315-01 (SEMI Staff) To call for new members to restart the activities of 3DP&I Steering Group to 3DP&I, Traceability and PIC Japan TC members.

Attachment: 05-05_TF Report - Steering WG v2023_3_r1

6 Old Business

6.1 SNARF Project Period Check

There are no SNARFs to be reviewed.

6.2 5 Years Review Check

6.2.1 SEMI G94-0113 (Reapproved 1118), Specification for Coin-Stack Type Tape Frame Shipping Container for 300 mm Wafer

Motion:	Approve the SNARF for: Reapproval of SEMI G94-0113 (Reapproved 1118) Specification for Coin-Stack Type Tape Frame Shipping Container for 300 mm Wafer
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By / 2nd:	Masahiro Tsuruya (iNEMI) / Kazunori Kato (AiT)
Discussion:	None
Vote:	4 in favor and 0 opposed. Motion Passed.

Attachment: SNARF_G94_Reapproval

Motion:	Authorize the Document ,Reapproval of SEMI G94-0113 (Reapproved 1118) Specification for Coin-Stack Type Tape Frame Shipping Container for 300 mm Wafer for Letter Ballot to Cycle 5-2023
By / 2nd:	Masahiro Tsuruya (iNemi) / Kazunori Kato (Advanced Interface Technology Corp.)
Discussion:	None
Vote:	4 in favor and 0 opposed. Motion Passed.

6.2.2 SEMI G64-1118, Specification for Full-Plated Integrated Circuit Leadframes (Au, Ag, Cu, Ni, Pd/Ni, Pd)

Motion:	Approve the SNARF for:Reapproval of G64-1118, Specification for Full-Plated Integrated Circuit Leadframes (Au, Ag, Cu, Ni, Pd/Ni, Pd)
By / 2nd:	Kazunori Kato (Advanced Interface Technology Corp.) / Mark Takahashi (retired)
Discussion:	None
Vote:	4 in favor and 0 opposed. Motion Passed.

Attachment: SNARF_G64_Reapproval

Motion:	Authorize the Document ,Reapproval of G64-1118, Specification for Full-Plated Integrated Circuit Leadframes (Au, Ag, Cu, Ni, Pd/Ni, Pd) for Letter Ballot Cycle 5-2023
By / 2nd:	Kazunori Kato (Advanced Interface Technology Corp.) / Mark Takahashi (retired)
Discussion:	None
Vote:	4 in favor and 0 opposed. Motion Passed.

6.3 Open Action Items for 3D Packaging & Integration Steering Group

Refer to 5.6

7 New Business

7.1 Proposal of New Activity

None

8 Action Item Review

8.1 Open Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20221214-01	3D Packaging & Integration 5 Year Review Task Force	To confirm documents and prepare SNARFs for these Reapproval Documents on the list by the next TC meeting.>Closed

8.2 New Action Items

The TC Chapter reviewed the following new action item.



<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20230315-01	SEMI Staff	To call for new members to restart the activities of 3DP&I Steering Group to 3DP&I, Traceability and PIC Japan TC members.

Next Meeting and Adjournment

The next meeting is scheduled for Wednesday, June 21,2023,13:30-16:00[JST] OVTCCM

See <http://www.semi.org/standards-events> for the current list of events.

Having no further business, a motion was made to adjourn. Adjournment was at 15:19.

Respectfully submitted by:

Mami Nakajo

Coordinator

SEMI Japan

Phone: +81.3.3222.5949

Email: mnakajo@semi.org

Minutes tentatively approved by:

Kazunori Kato (AiT), Co-chair	March 27,2023
Masahiro Tsuruya (iNEMI), Co-chair	March 27,2023
Haruo Shimamoto (ASIT), Co-chair	March 27,2023

Table 13 Index of Available Attachments^{#1}

<i>Title</i>	<i>Title</i>
01-02_Required Element Nov 2022_E+J (new template)	05-02_TF Report - 5yrs Review TF v2023_3_r1
02-01_20221214_3DPI-Japan_MeetingMinutes_approved	05-04_TF Report - PLP Encapsulation Characteristics TF v2023_3
03-01_NA 3DP&I Liaison Report Nov2022 v1	05-05_TF Report - Steering WG v2023_3_r1
03-02_3D P&I TW Liaison Report_20220902_v1	SNARF_G64_Reapproval
03-03_Staff Report March 2022 v1	SNARF_G94_Reapproval

#3 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact Mami Nakajo at the contact information above.